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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Joseph Paul Kuczynski : Date: May 30, 2002  
Group Art Unit: Unassigned : IBM Corporation  
Examiner: Unassigned : Intellectual Property Law  
Serial No.: Unassigned : Dept. 917, Bldg. 006-1  
Filed: Herewith : 3605 Highway 52 North  
Title: OPTICAL SUBASSEMBLY (OSA) HAVING A : Rochester, Minnesota 55901  
MULTIFUNCTIONAL ACRYLATE RESIN  
ADHESIVE FOR OPTOELECTRONIC MODULES,  
AND METHOD OF MAKING SAME

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97

Assistant Commissioner for Patents  
Washington, D.C. 20231  
Sir:

Applicants request that the information listed on the attached Form PTO-1449 be considered by the Office during the pendency of the above entitled application, pursuant to 37 C.F.R. §1.97. In accordance with 37 C.F.R. §1.97(h), the filing of this Information Disclosure Statement shall not constitute an admission that any information cited therein is, or is considered to be, material to patentability as defined in 37 C.F.R. §1.56(b). In the interest of full and complete disclosure to the Office, some or all of the art cited herein may not be considered by Applicant(s) or the Undersigned to be material under the new standard of materiality defined in 37 C.F.R. §1.56(b), enacted March 16, 1992, but may be material under the old standard of materiality defined in 37 C.F.R. §1.56(a), last amended on November 28, 1988, or may merely be technical background which may be of interest to the Examiner. In accordance with 37 C.F.R. §1.97(g), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made.

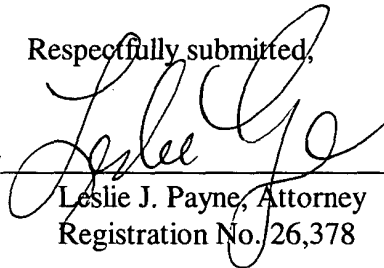
Serial No. Unassigned  
Docket No. ROC920020062US1

This Information Disclosure Statement is being filed under 37 C.F.R. §1.97(b)(1) within three months of the filing date of the present application. Accordingly no filing fee is required.

Date: May 30, 2002

Respectfully submitted,

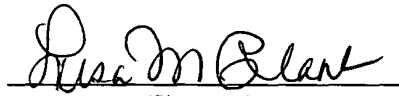
By

  
Leslie J. Payne, Attorney  
Registration No. 26,378

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Date of Deposit: May 31, 2002

I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office To Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to the Assistant Commissioner for Patents, Box Patent Application, Washington, D. C. 20231

  
(Signature)

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FORM PTO-1449 (Modified)

ATTY. DOCKET NO.  
ROC920020062US1SERIAL NO.  
UnassignedLIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S  
INFORMATION  
DISCLOSURE STATEMENT

APPLICANT: Joseph Paul Kuczynski

FILING DATE: Unassigned

GROUP: Unassigned



## REFERENCE DESIGNATION

## U.S. PATENT DOCUMENTS

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB- CLASS	FILING DATE (IF APPRO.)
AA	6 1 4 9 4 6 5	11/21/2000	Berg et al.	439	630	
AB						
AC						
AD						
AE						
AF						
AG						
AH						
AI						
AJ						
AK						

## FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB- CLASS	TRANSLATION	
					YES	NO
AL						
AM						
AN						
AO						

## OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

AR	W. K. Hogan et al., "A Novel Low-Cost Small-Form-Factor Transceiver Module", IBM Microelectronics MicroNews, Vol. 6, No. 3, pp. 26-33, Third Quarter 2000 ( <a href="http://www.chips.ibm.com/micronews/vol6_no3/MN_vol6_no3.pdf">http://www.chips.ibm.com/micronews/vol6_no3/MN_vol6_no3.pdf</a> ).
AS	U.S. Patent Application Serial No. 09/915,884, "Optical Subassembly (OSA) for Optoelectronic Modules, and Method of Making Same", Joseph P. Kuczynski, filed July 26, 2001. (Attorney Docket No. ROC920010031US1)
AT	U.S. Patent Application Serial No. 09/248,285, "UV Curable Adhesives Containing Ceramic Microspheres", Joseph P. Kuczynski, filed February 11, 1999. (Attorney Docket No. ROC919980236US1)

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.